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Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE **Application Number** 09/652430 STATEMENT BY APPLICANT September 1, 2000 **Filing Date** Use as many sheets as necessary) Sur, Biswajit First Named Inventor 2835 **Group Art Unit** Lea-Edmonds, Lisa **Examiner Name** JUL 0 8 2002 Attorney Docket No: 00884.319US1 Sheet 1 of 1

US PATENT DOCUMENTS									
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate			
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Examiner Initials*	Cite No 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
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